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# FLEXIBLE MOUNTING SUBSTRATE

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## Abstract

PURPOSE:To enable an ultrasonic wire bonding requiring no bump formation by providing, in the substrate portion corresponding to the end portion of a lead formed on the rear of a soft substrate, an opening for wire connection having a width smaller than the lead width, thereby constructing a flexible mounting substrate. CONSTITUTION:In the substrate 1 portion corresponding to the end portion of a lead 2 which was formed for connection of an electronic component such as a semiconductor IC chip 5 by patterning a conductive layer on the substrate 1 surface, an opening 3 for wire connection is formed which has a width smaller than that of this lead. With this, a ultrasonic wire bonding requiring no bump is enabled through the opening 3 for wire connection. Also, since no opening passing through to the surface and rear of the substrate 1 is formed, the resin encapsulation can be provided only at the side on which the electronic component such as the semiconductor IC chip 5 is mounted, thereby enabling a thin- type packaging.

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